# Monthly LabAdviser update: 24/10 2014

|  |  |  |
| --- | --- | --- |
| Updated Subject  | Contributor | Link to the updated pages |
| **Wet oxidation C1 furnace**Results using the new steamer | **Patama Pholprasit @danchip** | [Wet\_oxidation\_C1\_furnace](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/Oxidation/Wet_oxidation_C1_furnace#Test_of_the_wet_oxidation_by_steamer) |
| **Sandblasting**The machine may have been taken out of use due to safety concerns | **Jeper Hanberg****@danchip** | [Sandblasting](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Sandblasting) |
| **Danchip Contact Info**Change of optics in the LASER, write to toolchange@danchip.dtu.dk | **Jeper Hanberg****@danchip** | [Danchip\_Contact\_Info](http://labadviser.danchip.dtu.dk/index.php/LabAdviser#Danchip_Contact_Info) |
| **AFM**Newly installed AFM Icon equipment page | **Berit G. Herstrøm @danchip** | [AFM\_Icon](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/AFM%3A_Atomic_Force_Microscopy#AFM_Icon) |
| **LASER Micromachining**Values measured 10-10-2014:* Pulse energy VS repetition rate
* Average output power
* Fluency for picosecond wavelengths
 | **Chantal Silvestre****@danchip** | [PulseEnergy](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Laser_Micromachining_Tool/PulseEnergy)[101014\_AverageOutputPower.jpg](http://labadviser.danchip.dtu.dk/images/7/7b/101014_AverageOutputPower.jpg) [fluence](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Laser_Micromachining_Tool/fluence)  |
| **Dry Etch processing*** Hardware comparison page moved
* Temporary bonding to carrier wafer: moved from manuals to LabAdviser
* Optical endpoint system OES moved from manuals to LabAviser
 | **Jonas M. Lindhard @danchip** | [DryEtchProcessing](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DryEtchProcessing/OES)[Comparison](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DryEtchProcessing/Comparison)[Bonding](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DryEtchProcessing/Bonding)[OES](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DryEtchProcessing/OES) |
| **ICP metal**Updated value for Al etch rate | **Chantal Silvestre****@danchip** | [Aluminium\_etch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/Aluminium#Aluminium_etch) |
| **Thermal evaporation of Aluminum**How to evaporate thermal Al in Wordentec | **Katharina Nilson****@danchip** | [Thermal\_deposition\_of\_Al](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium/Thermal_deposition_of_Al) |
| **Multisource PDV**Data from acceptance test. | **Katharina Nilson****@danchip** | [Acceptance\_tests\_PVD\_co-sputter\_evaporation](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Multisource_PVD/Acceptance_tests_PVD_co-sputter_evaporation) |
| **Silicon deposition comparison**E-beam evaporation of Si in III-V dielectric evaporator has been added | **Katharina Nilson****@danchip** | [Deposition\_of\_Silicon](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon) |
| **Deposition of Titanium**E-beam evaporation of Ti in III-V dielectric evaporator has been addedSputter deposition of Ti in Sputter System Lesker has been added | **Katharina Nilson****@danchip** | [Deposition\_of\_Titanium](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Titanium) |
| **Deposition of Silver**E-beam evaporation of Ag in III-V dielectric evaporator has been added | **Katharina Nilson****@danchip** | [Deposition\_of\_Silver](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silver) |
| **Deposition of Ni**Sputter deposition of Ni in Sputter System Lesker has been added | **Katharina Nilson****@danchip** | [Deposition\_of\_Nickel](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Nickel) |
| **Deposition of Mo**Sputter deposition of Mo in Sputter System Lesker has been added | **Katharina Nilson****@danchip** | [Deposition\_of\_Molybdenum](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Molybdenum) |
| **Deposition of TiO2**E-beam evaporation of TiO2 in III-V dielectric evaporator has been added | **Katharina Nilson****@danchip** | [Deposition\_of\_Titanium\_Oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Titanium_Oxide) |
| **Deposition of Cu**Sputter deposition of Cu in Sputter System Lesker has been added | **Jeper Hanberg****@danchip** | [Deposition\_of\_Copper](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Copper) |

# Equipment Manuals updated in LabManager:

|  |
| --- |
| **Manual for LPCVD polysilicon furnace (4")** |
| **Manual for Black Magic PECVD (Carbon)** |  |
| **Manual for RIE2** |  |
| **Manual for AOE** |  |
| **Manual for ICP Metal Etch** |  |
| **Manual for RCA clean** |  |
| **Manual for Prism Coupler** |  |
| **Manual for III-V profiler** |  |
| **Manual for AFM Icon-PT** |  |

|  |
| --- |
|  |